

- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology



Product Summary

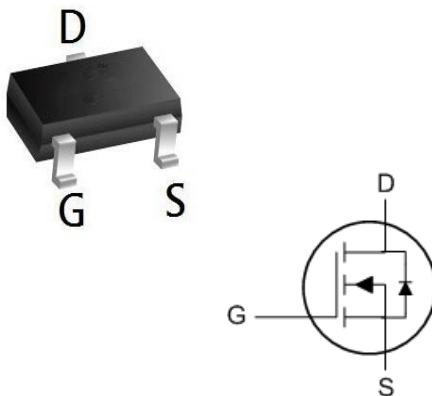
BVDSS	RDS(ON)	ID
100V	91 mΩ	3A

Description

The XXW3N10 is the high cell density trenched N-ch MOSFETs, which provides excellent RDS(ON) and efficiency for most of the small power switching and load switch applications.

The XXW3N10 meet the RoHS and Green Product requirement with full function reliability approved.

SOT23 Pin Configuration



Absolute Maximum Rating ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	100	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current $T_A = 25^\circ\text{C}$	I_D	3	A
Pulsed Drain Current ¹	I_{DM}	13.2	A
Power Dissipation $T_A = 25^\circ\text{C}$	P_D	1.5	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction to Ambient ²	$R_{\theta JA}$	83.3	$^\circ\text{C}/\text{W}$

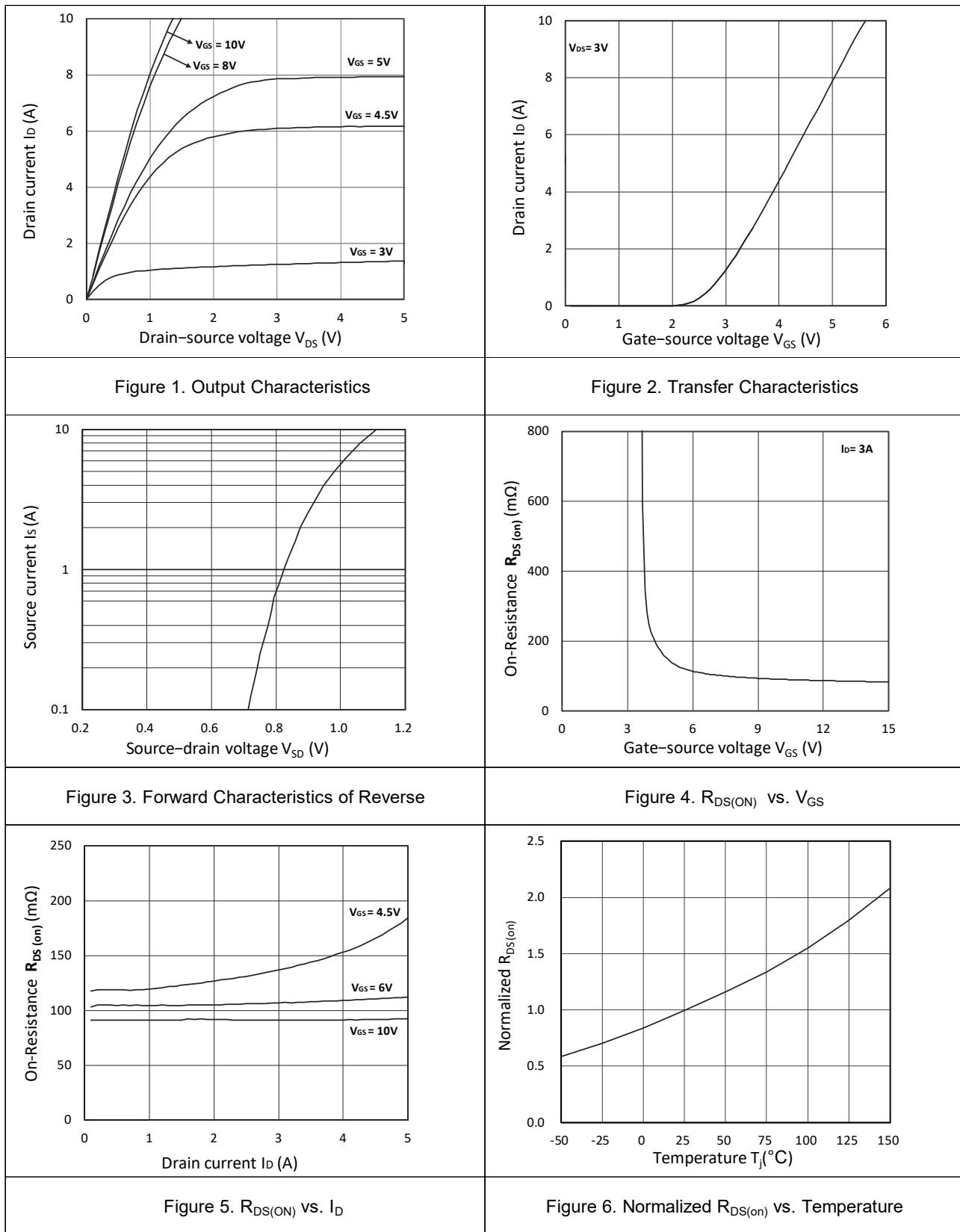
Electrical Characteristics (T_J=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	100	-	-	V
Gate-body Leakage Current	I _{GS}	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 100V, V _{GS} = 0V	-	-	1	μA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	1	1.65	2.5	V
Drain-Source On-state Resistance ³	R _{D(on)}	V _{GS} = 10V, I _D = 3A	-	91	130	mΩ
		V _{GS} = 6V, I _D = 2A	-	105	160	
		V _{GS} = 4.5V, I _D = 1A	-	120	190	
Dynamic Characteristics⁴						
Input Capacitance	C _{iss}	V _{GS} = 0V, V _{DS} = 50V, f = 1MHz	-	200	-	pF
Output Capacitance	C _{oss}		-	35	-	
Reverse Transfer Capacitance	C _{rss}		-	2.5	-	
Switching Characteristics⁴						
Total Gate Charge	Q _g	V _{DS} = 50V, V _{GS} = 10V, I _D = 3A	-	4	-	nC
Gate-Source Charge	Q _{gs}		-	0.6	-	
Gate-Drain Charge	Q _{gd}		-	1.4	-	
Turn-on Delay Time	t _{d(on)}	V _{DD} = 50V, V _{GS} = 10V, I _D = 3A, R _G = 3Ω	-	12.5	-	ns
Turn-on Rise Time	t _r		-	19.5	-	
Turn-off Delay Time	t _{d(off)}		-	20	-	
Turn-off Fall Time	t _f		-	29	-	
Source-Drain Diode characteristics						
Body Diode Voltage ³	V _{SD}	I _S = 3A, V _{GS} = 0V	-	-	1.2	V
Continuous Source Current	I _S		-	-	4.5	A

Notes:

- Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150°C.
- The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
- Pulse Test: Pulse width≤300μs, duty cycle≤2%.
- This value is guaranteed by design hence it is not included in the production test.

Typical Characteristics



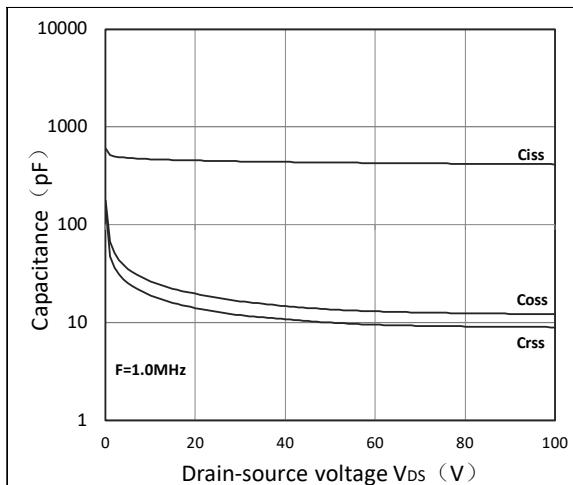
N-Ch 100V Fast Switching MOSFETs


Figure 7. Capacitance Characteristics

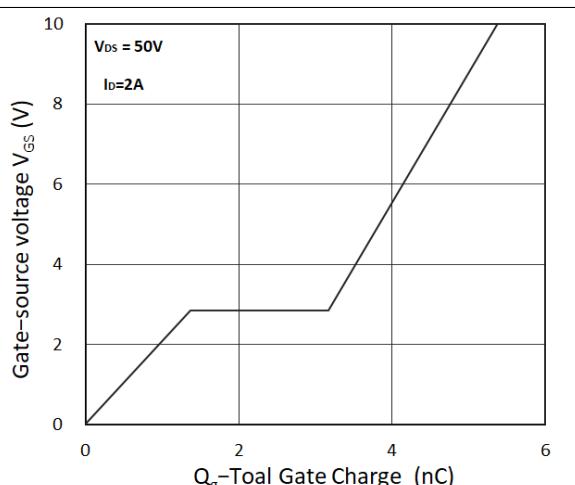
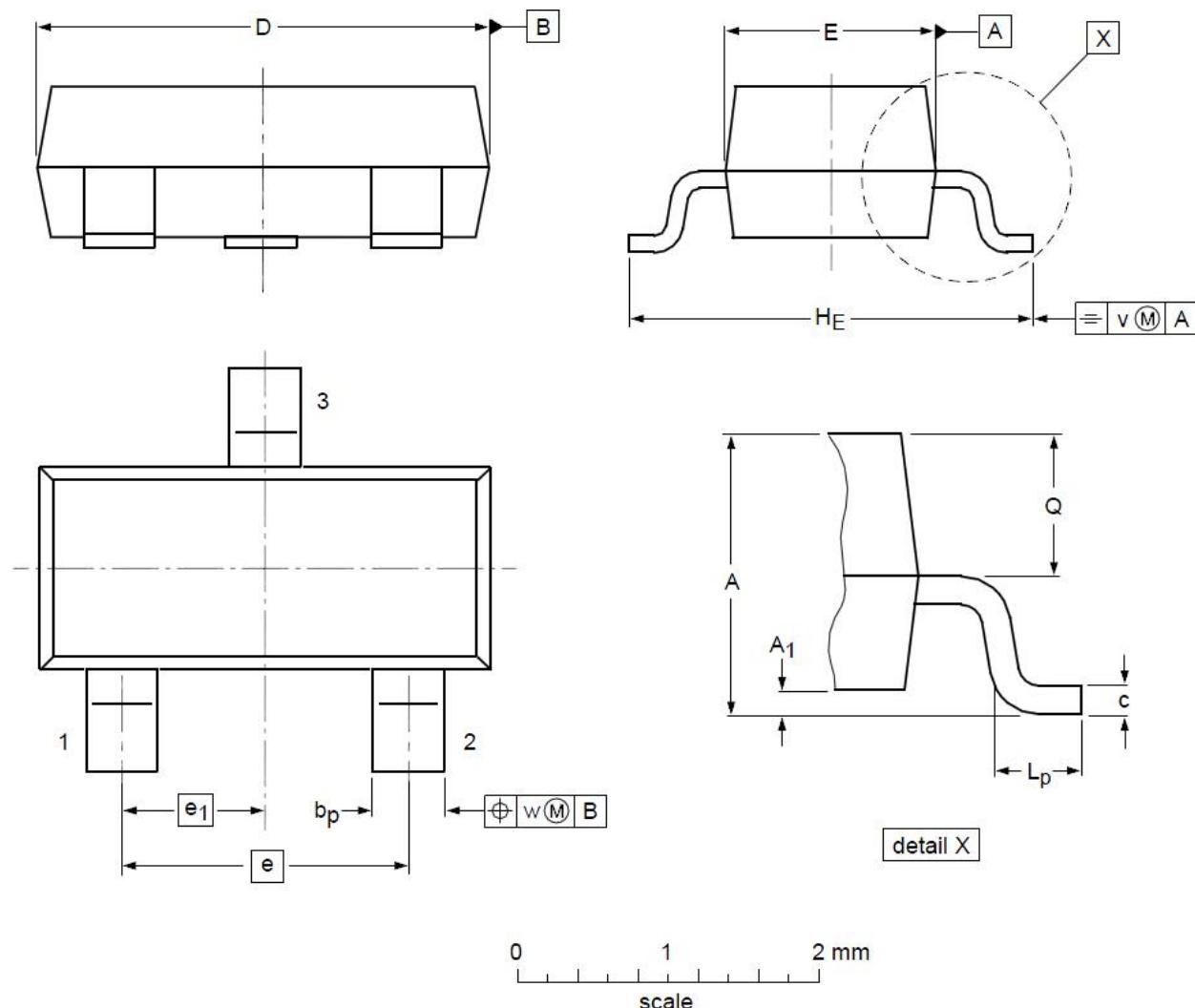


Figure 8. Gate Charge Characteristics

SOT23 Mechanical Data

DIMENSIONS (unit : mm)

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	0.90	1.01	1.15	A ₁	0.01	0.05	0.10
b _p	0.30	0.42	0.50	c	0.08	0.13	0.15
D	2.80	2.92	3.00	E	1.20	1.33	1.40
e	--	1.90	--	e ₁	--	0.95	--
H _E	2.25	2.40	2.55	L _p	0.30	0.42	0.50
Q	0.45	0.49	0.55	v	--	0.20	--
w	--	0.10	--				